



Material Content Data Sheet



Sales Product Name		IPZ40N04S5L-7R4		Issued		19. January 2018		
MA#		MA001338260						
Package		PG-TSDSON-8-32		Weight*		35.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.222	0.63	0.63	6311	6311
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88	
	non noble metal	zinc	7440-66-6	0.012	0.04		353	
	non noble metal	iron	7439-89-6	0.249	0.71		7065	
wire	non noble metal	copper	7440-50-8	10.102	28.69	29.45	286879	294385
	noble metal	gold	7440-57-5	0.031	0.09	0.09	875	875
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1065
	plastics	epoxy resin	-	1.931	5.48		54834	
	inorganic material	silicondioxide	60676-86-0	16.779	47.63	53.22	476471	532370
leadfinish	non noble metal	tin	7440-31-5	0.400	1.14	1.14	11367	11367
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2432	2432
solder	noble metal	silver	7440-22-4	0.009	0.03		262	
	non noble metal	tin	7440-31-5	0.007	0.02		210	
	non noble metal	lead	7439-92-1	0.353	1.00	1.05	10013	10485
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		17	
	non noble metal	zinc	7440-66-6	0.002	0.01		67	
	non noble metal	iron	7439-89-6	0.047	0.13		1334	
heat sink CLIP	non noble metal	copper	7440-50-8	1.908	5.42	5.56	54172	55590
	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2068	
	non noble metal	copper	7440-50-8	2.958	8.40	8.62	83988	86185
	*deviation	< 10%				Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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